Chun-Hao Chen

List of Publications by Year
in descending order

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14
papers

76
citations

1478505
6
h-index

1474206
9
g-index

14
all docs

14
docs citations

14
times ranked

25
citing authors

#	Article	IF	Citations
1	Evaluation of Corrosion Resistance of Ag-Alloy Bonding Wires for Electronic Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 146-153.	2.5	12
2	Mechanism of the Electromigration in Ag-Pd Alloy Bonding Wires. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2018, 49, 5904-5910.	2.2	9
3	Effect of Post-Weld Heat Treatment on the Solid-State Diffusion Bonding of 6061 Aluminum Alloy. Applied Sciences (Switzerland), 2021, 11, 9660.	2.5	9
4	Grain growth and twin formation in a Ag-4Pd alloy ribbon after annealing treatments. Journal of Alloys and Compounds, 2021, 863, 158619.	5.5	8
5	Ultrasonic Bonding of Ag and Ag-Alloy Ribbonâ€"An Innovative Alternative for High Power IC Packages. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1061-1068.	2.5	7
6	Improvement of Sn-3Ag-0.5Cu Soldered Joints Between Bi0.5Sb1.5Te3 Thermoelectric Material and a Cu Electrode. Journal of Electronic Materials, 2020, 49, 3391-3399.	2.2	7
7	Intermetallic Compounds at the Interfaces of Agâ€"Pd Alloy Stud Bumps With Al Pads. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1657-1665.	2.5	7
8	Microstructure evolution and failure mechanism of electromigration in Ag-alloy bonding wire. Journal of Alloys and Compounds, 2022, 913, 165266.	5.5	7
9	Electrolytic Migration of Ag-Pd Alloy Wires with Various Pd Contents. Journal of Electronic Materials, 2018, 47, 3634-3638.	2.2	5
10	Effects of Grain Size on the Ag Dissolution and Ion Migration of Ag-4Pd Alloy Wires. Journal of Electronic Materials, 2021, 50, 5955-5964.	2.2	3
11	Interfacial Reactions of Ag and Ag-4Pd Stud Bumps with Sn-3Ag-0.5Cu Solder for Flip Chip Packaging. Journal of Electronic Materials, 2021, 50, 249-257.	2.2	1
12	Interfacial reactions in Zn4Sb3/titanium diffusion couples. Journal of Alloys and Compounds, 2021, 881, 160630.	5.5	1
13	Applications of Ag-alloy stud bump for IC and LED packages. , 2014, , .		0
14	Intermetallic Growth at the Interfaces Between Zn4Sb3 Thermoelectric Material and Various Metallic Electrodes. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2022, 53, 136.	2.2	0